

**Maximum Ratings** (@ $T_A = 25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	$V_{CEO}$	-40	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current – Continuous (Note 5)	$I_C$	-600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	150	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Note: 5. Mounted on FR4 PC Board with minimum recommended pad layout.

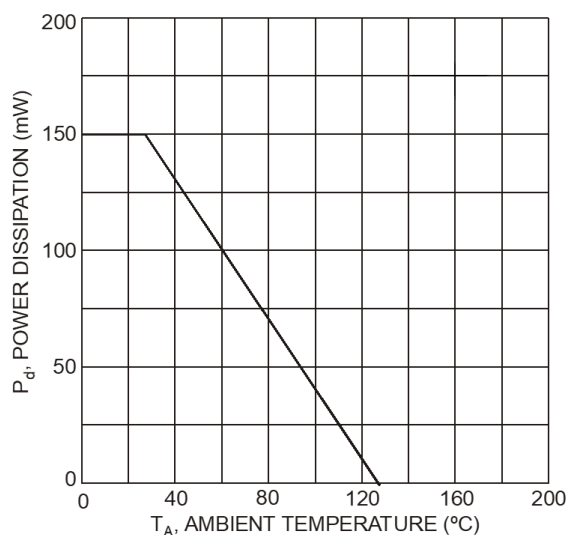
**Thermal Characteristics and Derating Information**


Fig. 1 Power Derating Curve, Total Package

**Electrical Characteristics** (@T<sub>A</sub> = 25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>					
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-40	—	V	I <sub>C</sub> = -100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-40	—	V	I <sub>C</sub> = -1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-5.0	—	V	I <sub>E</sub> = -100μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CEX</sub>	—	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V
Base Cutoff Current	I <sub>BL</sub>	—	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V
<b>ON CHARACTERISTICS (Note 6)</b>					
DC Current Gain	h <sub>FE</sub>	30 60 100 100 20	— — — 300 —	—	I <sub>C</sub> = -100μA, V <sub>CE</sub> = -1.0V I <sub>C</sub> = -1.0mA, V <sub>CE</sub> = -1.0V I <sub>C</sub> = -10mA, V <sub>CE</sub> = -1.0V I <sub>C</sub> = -150mA, V <sub>CE</sub> = -2.0V I <sub>C</sub> = -500mA, V <sub>CE</sub> = -2.0V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	-0.40 -0.75	V	I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	-0.75 —	-0.95 -1.30	V	I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	C <sub>cb</sub>	—	8.5	pF	V <sub>CB</sub> = -10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>eb</sub>	—	30	pF	V <sub>EB</sub> = -0.5V, f = 1.0MHz, I <sub>C</sub> = 0
Input Impedance	h <sub>ie</sub>	1.5	15	kΩ	V <sub>CE</sub> = -10V, I <sub>C</sub> = -1.0mA, f = 1.0kHz
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	
Small Signal Current Gain	h <sub>fe</sub>	60	500	—	
Output Admittance	h <sub>oe</sub>	1.0	100	μS	
Current Gain-Bandwidth Product	f <sub>T</sub>	200	—	MHz	V <sub>CE</sub> = -10V, I <sub>C</sub> = -20mA, f = 100MHz
<b>SWITCHING CHARACTERISTICS</b>					
Delay Time	t <sub>d</sub>	—	15	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA, V <sub>BE(off)</sub> = -2.0V, I <sub>B1</sub> = -15mA
Rise Time	t <sub>r</sub>	—	20	ns	
Storage Time	t <sub>s</sub>	—	225	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA, I <sub>B1</sub> = I <sub>B2</sub> = -15mA
Fall Time	t <sub>f</sub>	—	30	ns	

Note: 6. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

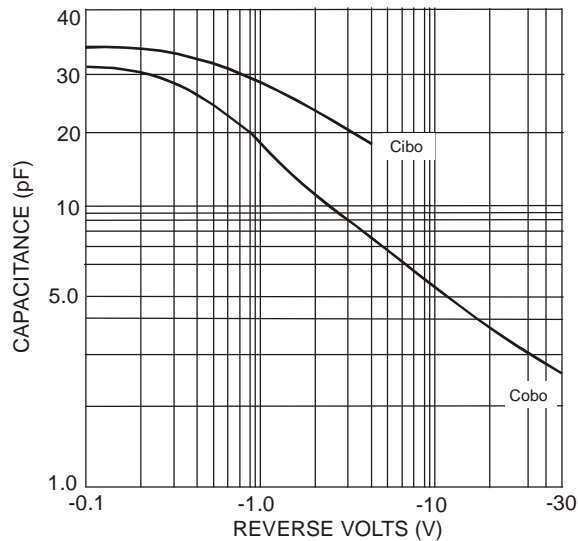


Fig. 2 Capacitances (Typical)

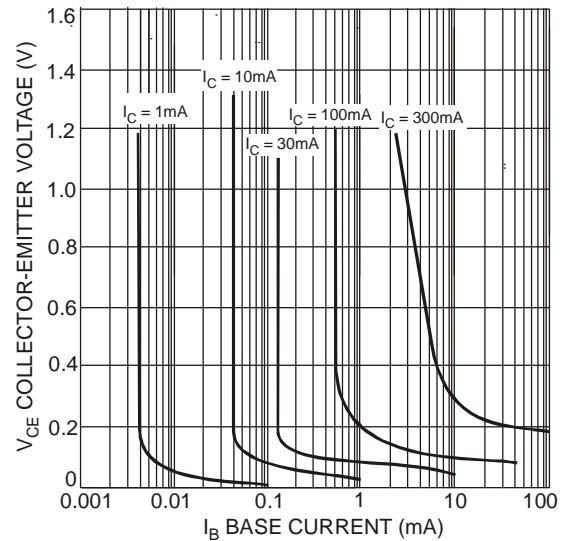


Fig. 3 Typical Collector Saturation Region

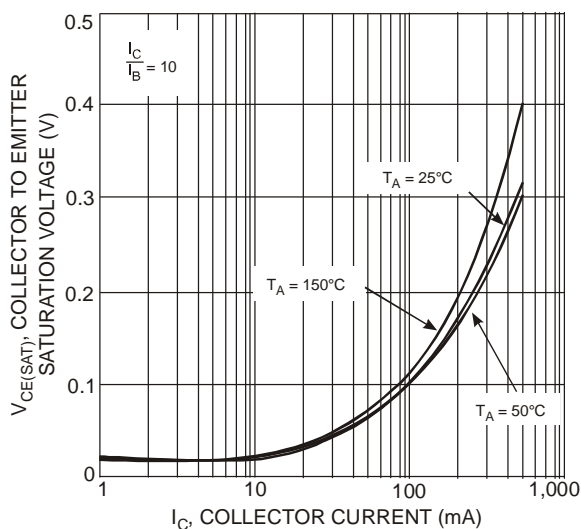


Fig. 4 Collector Emitter Saturation Voltage vs. Collector Current

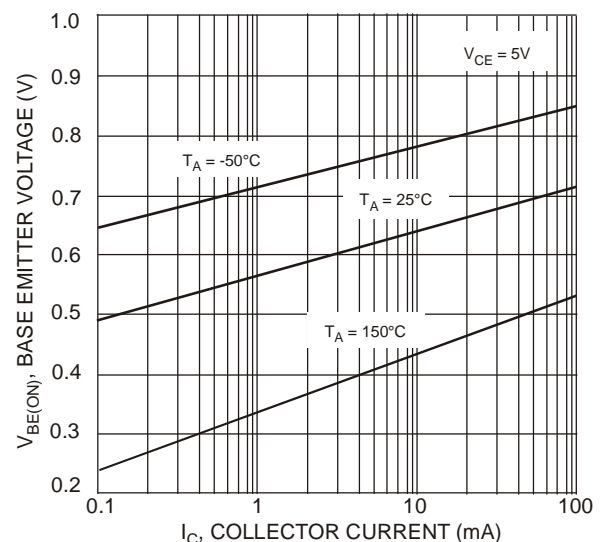


Fig. 5 Base-Emitter Voltage vs. Collector Current

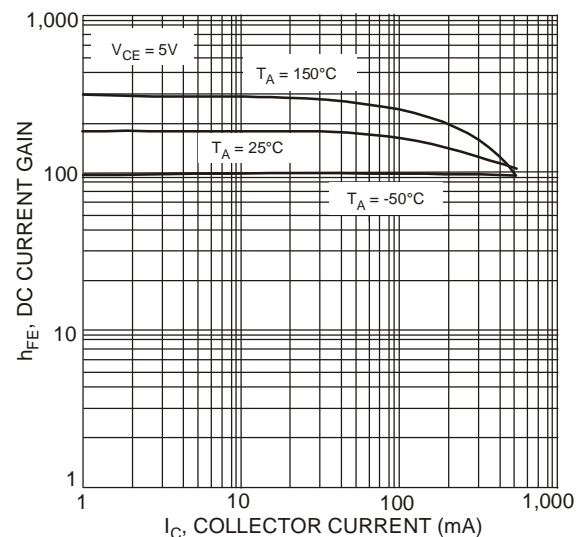


Fig. 6 DC Current Gain vs. Collector Current

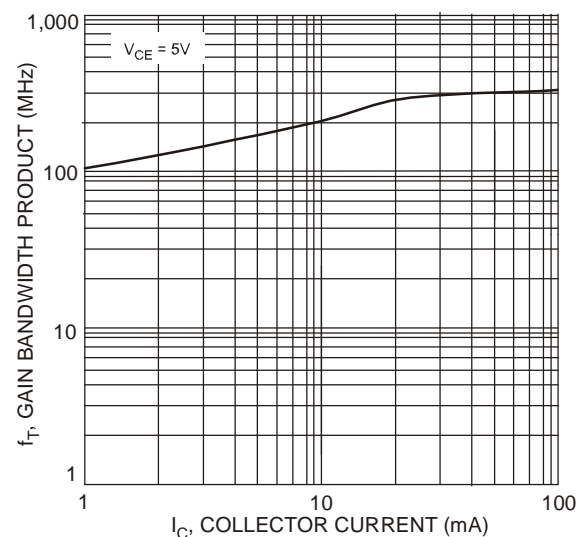
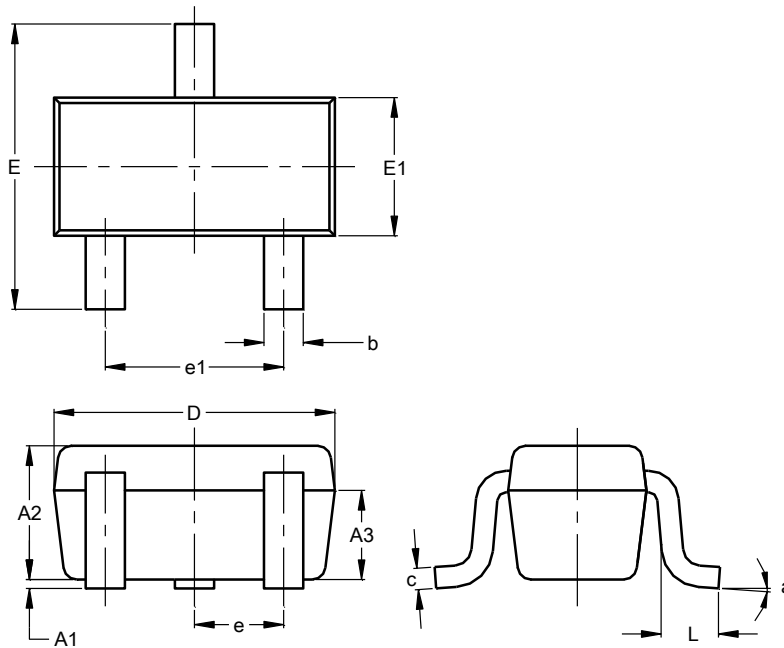


Fig. 7 Gain Bandwidth Product vs. Collector Current

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SOT523

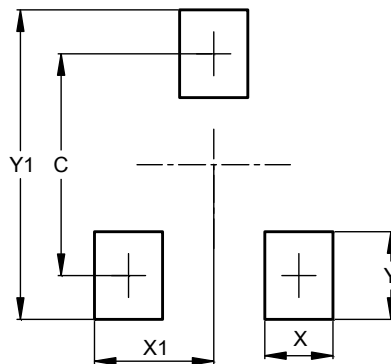


SOT523			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.60	0.80	0.75
A3	0.45	0.65	0.50
b	0.15	0.30	0.22
c	0.10	0.20	0.12
D	1.50	1.70	1.60
E	1.45	1.75	1.60
E1	0.75	0.85	0.80
e	0.50 BSC		
e1	0.90	1.10	1.00
L	0.20	0.40	0.33
a	0°	--	8°
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SOT523



Dimensions	Value
C	1.29
X	0.40
X1	0.70
Y	0.51
Y1	1.80

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